



# Material Composition Declaration

## EPC2025

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	6.4 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	5.9778	93.60	96.65	935979
	Silicon oxide	7631-86-9	0.0242	0.38		3790
	Silicon nitride	12033-89-5	0.0088	0.14		1378
	Gallium nitride	25617-97-4	0.0557	0.87		8725
	Aluminum	7429-90-5	0.0386	0.60		6050
	Aluminum nitride	24304-00-5	0.0153	0.24		2388
	Titanium	7440-32-6	0.0008	0.01		130
	Titanium nitride	25583-20-4	0.0034	0.05		526
	Copper	7440-50-8	0.0013	0.02		201
	Tungsten	7440-33-7	0.0013	0.02		207
	Polyimide		0.0457	0.72		7150
Under Bump Metal	Titanium	7440-32-6	0.0003	0.01	0.45	53
	Nickel	7440-02-0	0.0101	0.16		1577
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.0182	0.29		2856
Solder Bump	Tin	7440-31-5	0.1805	2.83	2.90	28263
	Silver	7440-22-4	0.0046	0.07		725
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			6.4	100.00	100	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.